Abstracts

Millimeter-Wave Packaging

H.J. Kuno and T.A. Midford. "Millimeter-Wave Packaging." 1992 MTT-S International Microwave Symposium Digest 92.3 (1992 Vol. III [MWSYM]): 1507-1508.

In the development of millimeter-wave devices and components, package design and implementation have often lagged behind the development of other elements such as active devices, matching circuits, and integrated circuits. The result has been the surfacing of sometimes significant packaging issues late in the product development cycle, often with the result of substantial performance compromise. This situation is partly a result of having fielded only a very limited number of millimeter-wave components and systems, thus negating the need for extensive packaging development and a packaging infrastructure. It is noteworthy that no commercial RF packages exist for operation at frequencies above 20 GHz and significant performance degradation is already evident at X-band.

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